



Advance Product Change Notification

201403014AU01

Issue Date: 28-Apr-2014

UPDATE

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QUALITY

Management Summary

For the PCF8563T/5 Real Time Clock (RTC), we will change the wafer fab from TSMC fab 2 to Vanguard and introduce a 2nd assembly and final test location (in addition to NXP-APB) as ASEN.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input checked="" type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

PCF8563T/5 wafer fab and final test location and assembly site change

Details of this Planned Change

1- Currently the PCF8563T/5 Real Time Clock (RTC) is being diffused in TSMC fab2. We will transfer the production to Vanguard. The two fabs are in close proximity to each other. We have already fabrication of products in the same process running in Vanguard for long time. Fabrication technology and feature size is identical. The quality and reliability is absolutely comparable to the current fab.

2- A new assembly fab site will be added. ASEN in China will be utilized in addition to NXP Assembly Plant Bangkok (APB).

3- A new final test site and test system will be added, too. The new testing site will be ASEN in China (instead of NXP Assembly Plant Bangkok (APB)). The test system (ATE) will change from SPEA 372 to Nextest Magnum (Nextest is a Teradyne company). Test coverage and quality is not impacted by this change.

Why do we Plan this Change

1- To produce the products in a more state-of-the-art wafer fab. TSMC fab 2 is producing on 6" wafers while the production at Vanguard is on 8" wafers.

2- To utilize state-of-the art test systems and ensure production capacity in assembly and test.

Identification of Affected Products

Top side marking

On the package, the 2nd line will start with an "F" instead of an "A".

Product Availability

Sample Information

Sample planning follows with the final PCN

Production

Planned first shipment 31-Jul-2014

Update Information

Added the new assembly location which was accidentally missed at the first version of the PCN.

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201403014A	17-Mar-2014		PCF8563T/5 wafer fab and final test location change

Timing and Logistics

The Self Qualification Report will be ready on 30-Jun-2014.

The Final PCN is planned to be issued on: 30-Jun-2014.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 28-May-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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